


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H743VIH6	PODY*450XXXY	A	9996	2018-07-12
	Amount	UoM	Unit type	ST ECOPACK Grade
	126.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	8x8	183	No lead	
Comment	Package : A08Q TFBGA 8X8 100L F10X10 0.8 MM P DM00254729			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	PODY*450XXXY				5999999.0	1000000.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.485	mg	supplier	die	Silicon (Si)	7440-21-3		9.743	mg	929232	77325
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	8393	698
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	26323	2190
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	95	8
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	4292	357
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	763	63
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	95	8
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	30806	2563
				supplier	CORE	Glass Cloth	65997-17-3		2.560	mg	84270	20318
				SUBSTRATE (DS7409HGB)	M-011 Other inorganic materials	30.380	mg	supplier	CORE	Copper (Cu)	7440-50-8	
supplier	CORE	Epoxy	28906-96-9						0.896	mg	29494	7111
supplier	CORE	Flame resistant resin	223769-10-6						0.640	mg	21067	5080
supplier	CORE	Heat resistant resin	25722-66-1						0.640	mg	21067	5080
supplier	CORE	Silica filler	7631-86-9						1.152	mg	37921	9143
supplier	CORE	Metal Hydroxide	Proprietary						0.512	mg	16854	4064
supplier	SOLDERMASK (AUS320)	Solvent naphtha (petroleum), Heavy arom.	64742-94-5						1.666	mg	54855	13226
supplier	SOLDERMASK (AUS320)	Naphthalene	91-20-3						0.176	mg	5785	1395
supplier	SOLDERMASK (AUS320)	Phosphinoxide derivative	Proprietary						0.061	mg	1995	481
supplier	SOLDERMASK (AUS320)	Talc containing no asbestiform fibers	14807-96-6						0.454	mg	14960	3607
supplier	SOLDERMASK (AUS320)	Barium sulfate	7727-43-7						0.757	mg	24934	6012
supplier	SOLDERMASK (AUS320)	Dipropylene glycol monomethyl ether	34590-94-8						0.454	mg	14960	3607
supplier	CU FOIL	Copper (Cu)	7440-50-8						13.114	mg	431649	104075
supplier	NI PLATING	Nickel (Ni)	7440-02-0						0.737	mg	24253	5848
supplier	AU PLATING	Gold (Au)	7440-57-5						0.160	mg	5260	1268
DIE ATTACH (2300)	M-011 Other inorganic materials	1.478	mg					supplier	GLUE	Silver (Ag)	7440-22-4	
				supplier	GLUE	Tetramethylene dimethacrylate	2082-81-7		0.074	mg	50000	586
BONDING WIRE (Au wire)	M-011 Other inorganic materials	1.197	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1.197	mg	1000000	9499
SOLDERBALL (SAC 105)	M-011 Other inorganic materials	35.598	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		35.064	mg	985000	278283
				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.356	mg	10000	2825
ENCAPSULATION (GE-100LFC5)	M-011 Other inorganic materials	46.863	mg	supplier	SOLDERBALL	Copper (Cu)	7440-50-8		0.178	mg	5000	1413
				supplier	MOLDING COMPOUND	Silica vitreous	60676-86-0		41.409	mg	885000	328645
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		1.897	mg	40000	15055
				supplier	MOLDING COMPOUND	Phenol resin	Proprietary		1.423	mg	30000	11291
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.237	mg	5000	1882
supplier	MOLDING COMPOUND	Metal hydroxide	Proprietary		1.423	mg	30000	11291				
supplier	MOLDING COMPOUND	Crystalline silica	14808-60-7		0.474	mg	10000	3764				